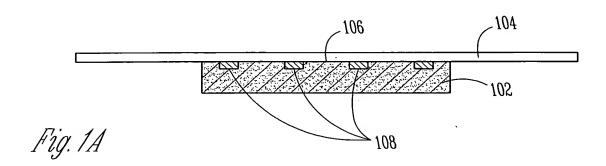
TITLE: DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGE HAVING A MOISTURE BARRIER STRUCTURE

INVENTORS NAME: Qing Ma DOCKET NO.: 884.803US2

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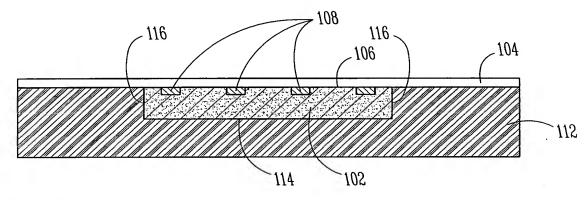


Fig. 1B

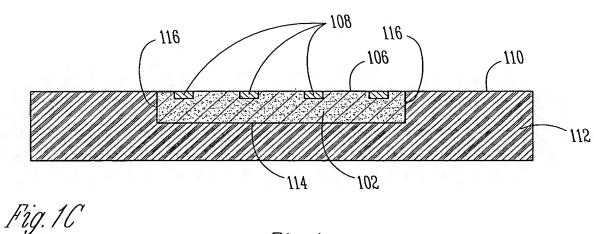


Fig. 1

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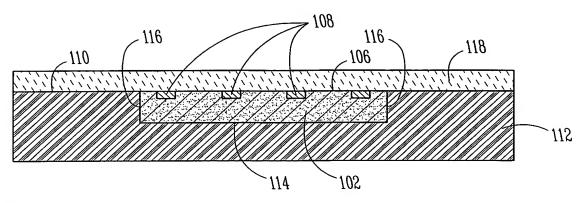


Fig. 1D

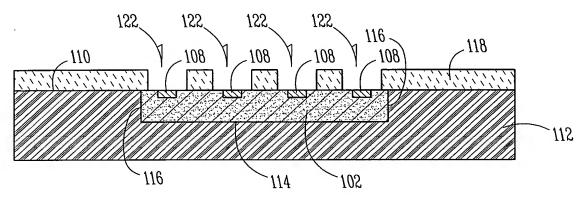


Fig. 1E

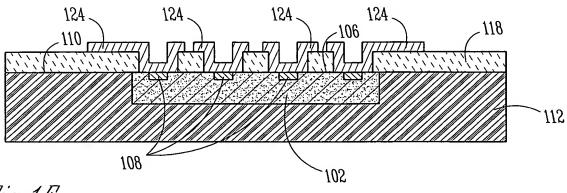
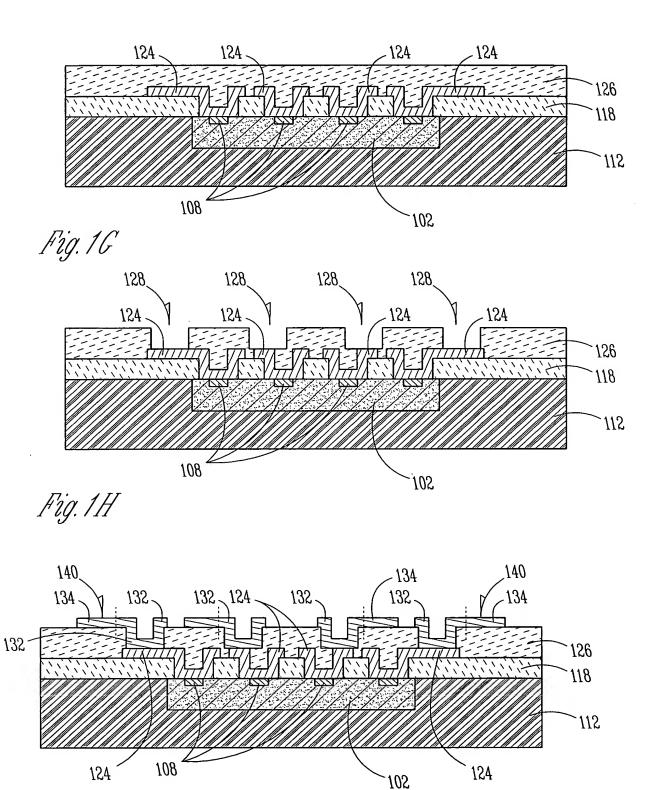
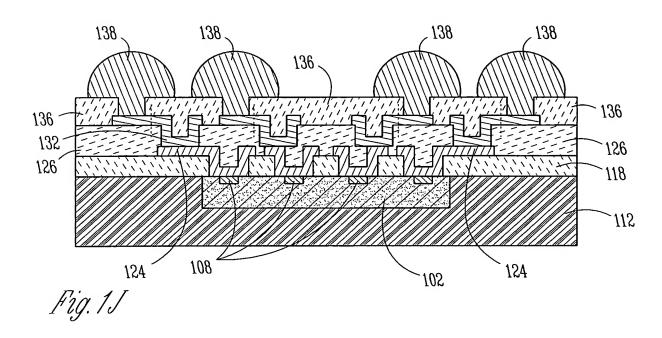


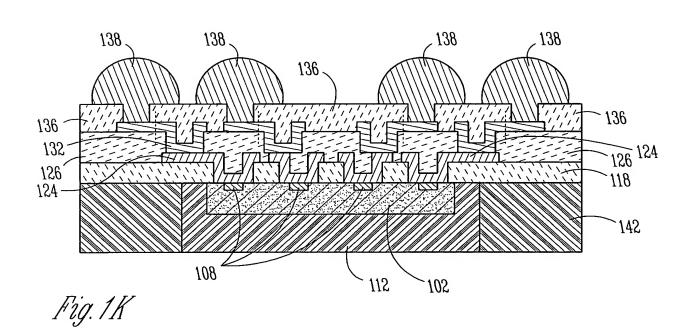
Fig. 1F

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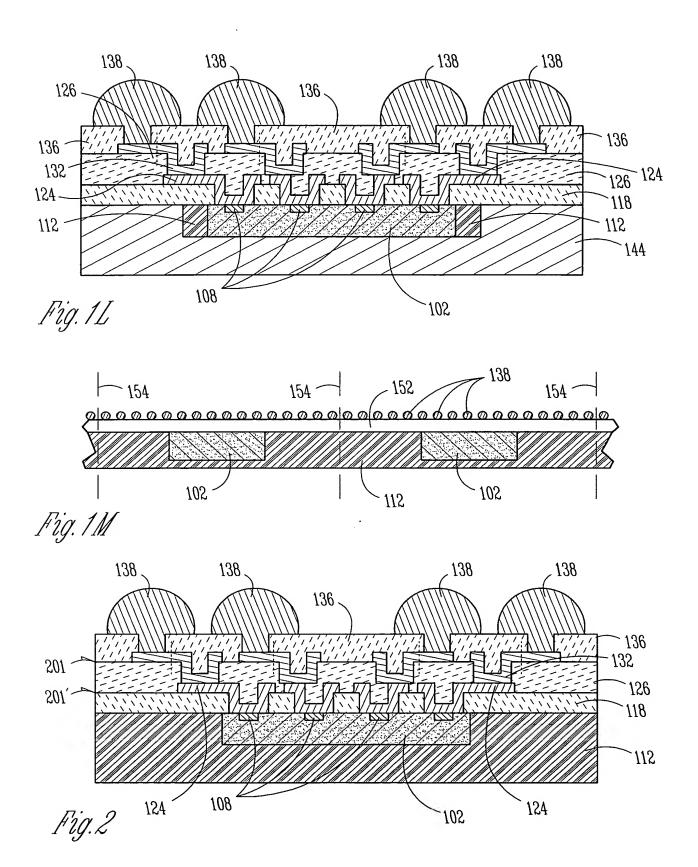


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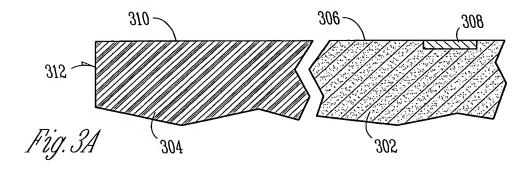


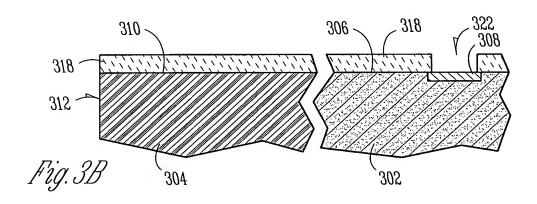


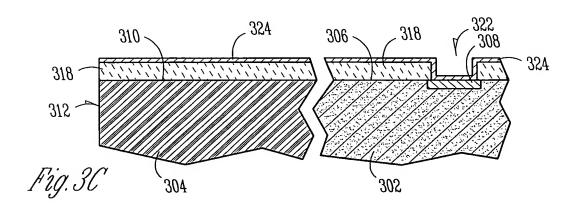
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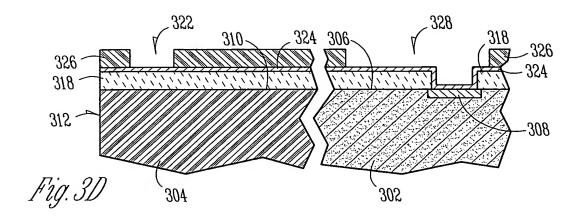
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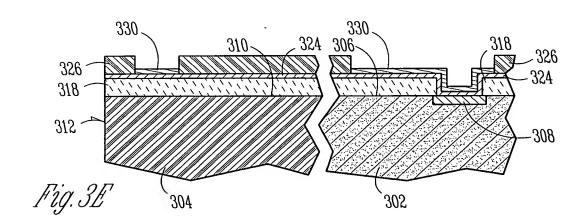


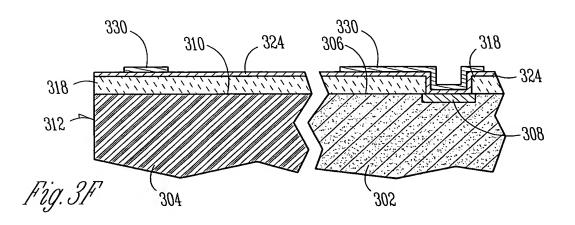




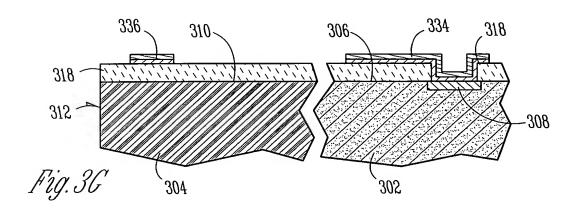
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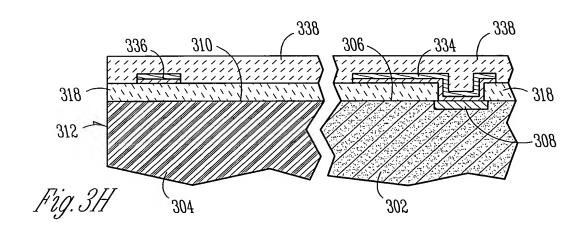


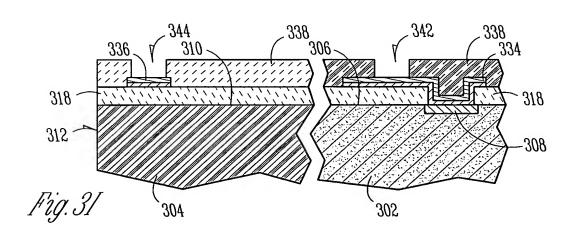




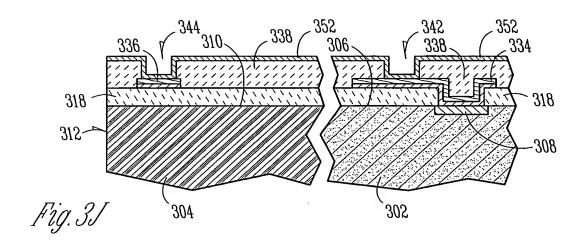
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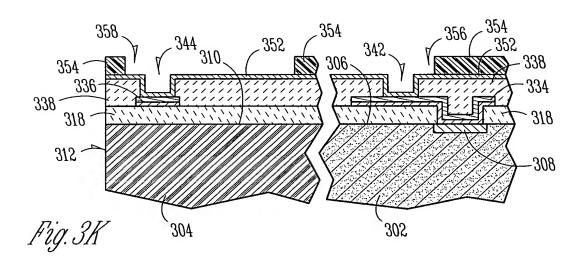


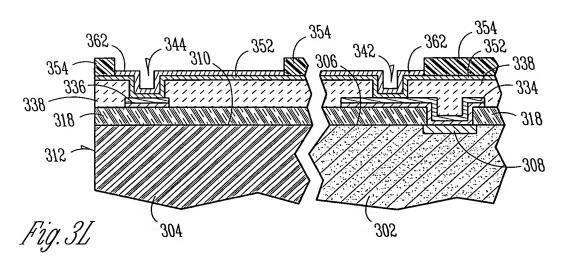




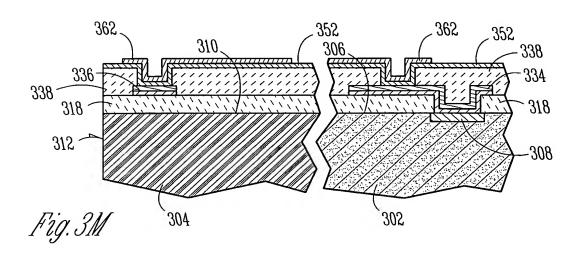
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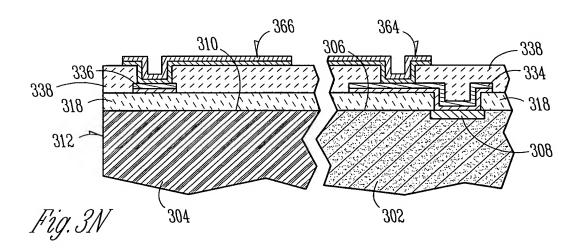




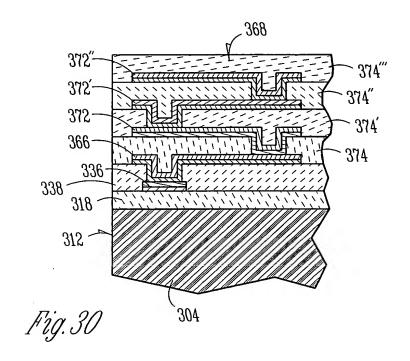


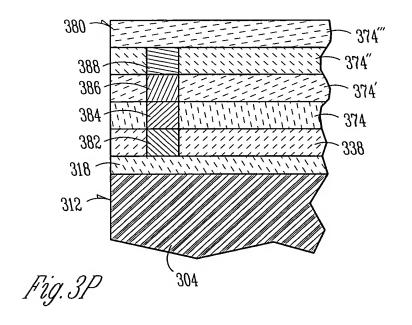
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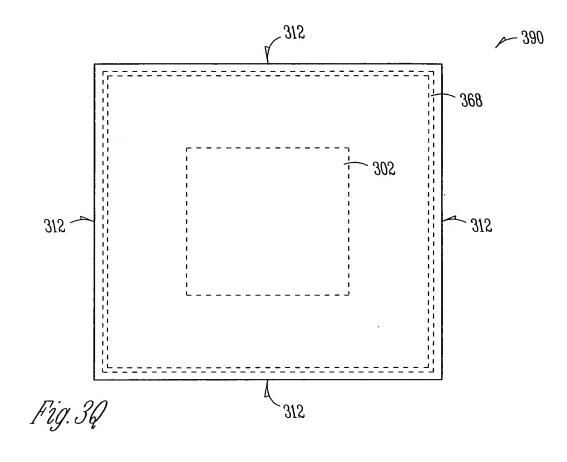


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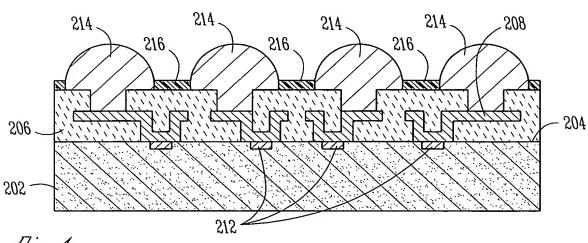


Fig. 4 (Prior Art)

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